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P57015**IN THE CLAIMS**

Please amend claim 12 as follows:

1           1. (Original) A method of manufacturing an electromagnetic wave shielding  
2 filter, the method comprising:  
3           preparing a metal plate for plating;  
4           forming an insulating layer on an upper surface of the metal plate, the insulating  
5 layer having a mesh pattern;  
6           forming a plating layer on a remaining upper surface of the metal plate on which  
7 the insulating layer is not formed;  
8           arranging an adhesive film on the metal plate having the insulating layer and the  
9 plating layer;  
10          adhering the adhesive film to upper surfaces of the insulating layer and the plating  
11 layer; and  
12          separating the adhesive film from the metal plate so that the plating layer is  
13 adhered to a lower surface of the adhesive film, the plating layer being in the form of a  
14 mesh.

1           2. (Original) The method according to claim 1, wherein the metal plate  
2 comprises an alloy selected from at least one of SUS, a titanium alloy, a nickel alloy, a  
3 copper alloy, and an iron alloy, the metal plate acting as a seed layer for electrolytic

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4     plating.

1           3. (Original) The method according to claim 1, wherein the insulating layer is  
2     formed by oxide coating.

1           4. (Original) The method according to claim 1, wherein the plating layer  
2     comprises at least one of copper or silver.

1           5. (Original) The method according to claim 1, wherein the adhesive film  
2     comprises polyethylene terephthalate (PET).

1           6. (Original) The method according to claim 1, wherein the adhesive film  
2     comprises a polymer film.

1           7. (Original) The method according to claim 1, wherein a binding force of the  
2     plating layer to the adhesive film is stronger than a binding force of the plating layer to  
3     the metal plate.

1           8. (Original) A method of manufacturing an electromagnetic wave shielding  
2     filter, the method comprising:  
3         preparing a metal plate for plating;

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4 forming a photoresist layer on an upper surface of the metal plate, the photoresist  
5 layer having a mesh pattern;

6 forming a plating layer on a remaining upper surface of the metal plate on which  
7 the photoresist layer is not formed;

8 removing the photoresist layer from the metal plate;

9 arranging an adhesive film on the metal plate having the plating layer;

10 adhering the adhesive film to an upper surface of the plating layer; and

11 separating the adhesive film from the metal plate so that the plating layer is  
12 adhered to a lower surface of the adhesive film, the plating layer being in the form of a  
13 mesh.

1 9. (Original) The method according to claim 8, wherein the metal plate  
2 comprises an alloy selected from at least one of SUS, a titanium alloy, a nickel alloy, a  
3 copper alloy, and an iron alloy, the metal plate acting as a seed layer for electrolytic  
4 plating.

1 10. (Original) The method according to claim 8, wherein the adhesive film  
2 comprises a polymer film.

1 11. (Original) A method of manufacturing an electromagnetic wave shielding  
2 filter, the method comprising:

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3 preparing a substrate;  
4 adhering a metal foil to an upper surface of the substrate;  
5 forming a photoresist layer on an upper surface of the metal foil, the photoresist  
6 layer having a mesh pattern;  
7 forming a plating layer on a remaining upper surface of the metal foil on which the  
8 photoresist layer is not formed;  
9 removing the photoresist layer from the metal foil;  
10 arranging an adhesive film on the metal foil having the plating layer;  
11 adhering the adhesive film to an upper surface of the plating layer; and  
12 separating the adhesive film from the metal foil so that the plating layer is adhered  
13 to a lower surface of the adhesive film, the plating layer being in the form of a mesh.

1 12. (Currently Amended) The method according to claim 11, wherein the metal  
2 [[plate]] foil comprises an alloy selected from at least one of SUS, a titanium alloy, a  
3 nickel alloy, a copper alloy, and an iron alloy, the metal plate acting as a seed layer for  
4 electrolytic plating.

1 13. (Original) The method according to claim 11, wherein the plating layer  
2 comprises at least one of copper or silver.

1 14. (Original) The method according to claim 11, further comprising blackening

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2 the surface of the plating layer to increase contrast, after forming the plating layer.

1 15. (Original) The method according to claim 11, wherein the adhesive film  
2 comprises PET.

1 16. (Original) The method according to claim 11, wherein a binding force of the  
2 plating layer to the adhesive film is stronger than a binding force of the plating layer to  
3 the substrate or the metal foil.

1 17. (Original) The method according to claim 11, wherein the adhesive film  
2 comprises a polymer film.

1 18. (Original) An electromagnetic wave shielding filter, manufactured by  
2 preparing a substrate, forming a meshed plating layer on an upper surface of the substrate,  
3 adhering an adhesive film to an upper surface of the plating layer, and separating the  
4 adhesive film from the substrate so that the plating layer is adhered to a lower surface of  
5 the adhesive film.

1 19. (Original) The electromagnetic wave shielding filter according to claim 18,  
2 wherein the substrate is a metal plate arranged to act as a seed layer for electrolytic  
3 plating.

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1           20. (Original) The electromagnetic wave shielding filter according to claim 18,  
2           wherein the metal plate comprises an alloy selected from at least one of SUS, a titanium  
3           alloy, a nickel alloy, a copper alloy, or an iron alloy.

1           21. (Original) The electromagnetic wave shielding filter according to claim 18,  
2           wherein the plating layer comprises at least one of copper or silver.

1           22. (Original) The electromagnetic wave shielding filter according to claim 18,  
2           wherein the surface of the plating layer is blackened.

1           23. (Original) The electromagnetic wave shielding filter according to claim 18,  
2           wherein the adhesive film comprises PET.

1           24. (Original) The electromagnetic wave shielding filter according to claim 18,  
2           wherein the adhesive film comprises a polymer film.

1           25. (Original) The electromagnetic wave shielding filter according to claim 18,  
2           wherein a transparent layer containing an acrylic solid is further arranged on the upper  
3           surface of the meshed plating layer to cover voids in the meshed plating layer.

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1           26. (Original) The electromagnetic wave shielding filter according to claim 25,  
2           wherein the transparent layer comprises at least one of an acrylate or a butyl carbitol.

1           27. (Original) The electromagnetic wave shielding filter according to claim 25,  
2           wherein the transparent layer comprises 10% or less of an adhesive.